

	U	1	Document ID	Title	Current OR	Current XRef	Ret.
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4302268 A	Process for preparing flexible printed-circuit board	156/238	156/249 ; 216/20	
9	<input type="checkbox"/>	<input type="checkbox"/>	US 4933042 A	Method for packaging integrated circuit chips employing a polymer film	156/239	156/275.5 ; 156/275.7	
10	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5045141 A	Method of making solderable printed circuits formed without plating	156/240	156/330 ; 174/257	
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5326414 A	Method for making electrostatic RF absorbant circuit carrier assembly	156/242	156/244.11 ; 156/245	
12	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5468324 A	Spin-on and peel polymer film method of data recording duplication and	156/247	264/2.1 ; 369/284	
13	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5749997 A	Composite bump tape automated bonding method and bonded structure	156/249	156/275.7 ; 156/295	
14	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4701236 A	Method of manufacturing an electronic identification card	156/252	156/253 ; 156/261	
15	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5690773 A	Method for the manufacture of a contact-free or hybrid card	156/267	156/297 ; 156/300	
16	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4765860 A	Method of making a flexible base plate for printed circuit board	156/272.6	156/274.8 ; 156/307.3	
17	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4880486 A	Method for mounting electronic parts	156/273.5	156/275.5 ; 156/275.7	
18	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5578527 A	Connection construction and method of manufacturing the same	156/273.9	156/325 ; 438/119	
19	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4054479 A	Additive process for producing printed circuit elements using a	156/280	156/230 ; 156/249	
20	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4214936 A	Lamination process	156/302	156/351 ; 156/358	
21	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 4662973 A	Continuous process for preparing reinforced resin laminates	156/307.4	156/247 ; 156/313	
22	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5296074 A	Method for bonding small electronic components	156/309.9	156/312 ; 156/320	
23	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 3925138 A	Process for preparing an insulating substrate for use in printed circuits	156/313	156/150 ; 156/246	
24	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5454484 A	Dispersion-based heat-sealable coating	156/320	156/321.7	

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Default operator: OR ☐ Highlight all hit terms initially

1 and 2 and 3 and rf

☒ BRS term
 ☒ IS&R term
 ☐ Image
 ☐ Text

	U	1	Document ID	Title	Current OR	Current XRef	Ret.
1	<input type="checkbox"/>	<input type="checkbox"/>	US 5779839 A	Method of manufacturing an enclosed transceiver	156/213	156/308.4 ; 29/855	
2	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5776278 A	Method of manufacturing an enclosed transceiver	156/213	156/308.4 ; 29/855	
3	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6045652 A	Method of manufacturing an enclosed transceiver	156/292	156/278 ; 340/10.1	
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5448110 A	Enclosed transceiver	257/723	257/724 ; 340/10.1	
5	<input type="checkbox"/>	<input type="checkbox"/>	US 5144747 A	Apparatus and method for positioning an integrated circuit chip within a	29/834	257/700 ; 257/713	

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